

MRS Elects Officers, Councillors for 1998

Members of the Materials Research Society have elected two officers and six councillors to join the 1998 Council, which consists of the executive committee and 15 councillors. The annual election ended October 10, 1997.

1998 MRS Officers

President

Robert J. Nemanich (1998)
North Carolina State University

Immediate Past President

Robert Hull (1998)
University of Virginia

Vice President (President-Elect)

*Ronald Gibala (1998)
University of Michigan

Secretary: *Chuang Chuang Tsai (1999)

Applied Komatsu Technology

Treasurer: Alan J. Hurd (1998)

Sandia National Laboratories

1998 MRS Councillors

Cammy R. Abernathy (1998)
University of Florida

Harry A. Atwater (1998)
California Institute of Technology

***Michael J. Aziz (2000)**
Harvard University

***Katayun Barnak (2000)**
Lehigh University

Theodore M. Besmann (1999)
Oak Ridge National Laboratory

***David J. Eaglesham (2000)**
Bell Laboratories, Lucent Technologies

Martin L. Green (1998)
Bell Laboratories, Lucent Technologies

***Alexander H. King (2000)**
State University of NY at Stony Brook

***Karen Maex (2000)**
IMEC, Belgium

Amy J. Moll (1999)
Hewlett Packard

Virginia M. Oversby (1998)
VMO Konsult

Tim Sands (1999)
University of California—Berkeley

Lyle H. Schwartz (1998)
Associated Universities, Inc.

***Alan I. Taub (2000)**
Ford Motor Company

James S. Williams (1998)
Australian National University

(Terms of office expire at the end of the years indicated in parentheses.)

*Newly elected.

MRS

Graduate Student Award Finalists Compete at 1997 MRS Fall Meeting

Twenty-six finalists will compete for the MRS Graduate Student Awards to be presented during the awards ceremony on Wednesday, December 3, at 6:00 p.m., in the Boston Marriott Hotel, Salon E at the 1997 MRS Fall Meeting. The Graduate Student Award Special Talk Session, in which each finalist gives a 10-minute presentation, will be held on Monday, December 1, at noon.

Following is the list of finalists, their places of study, titles of papers, and the symposium or symposia in which each finalist is participating:

Kathleen M. Amm, Florida State University, "Processing and Properties of (Hg,Bi)Ba₂Ca₂Cu₃O₇ Tapes" and "Synthesis and Processing of Bi-Doped Hg-1223 Superconductor" (Symposium T)

Martin Z. Bazant, Harvard University, "Environment-Dependent Interatomic Potential for Bulk Silicon" (Symposium R)

J. D. Brown, North Carolina State University, "The First Nitride Laser Diode on Silicon Carbide" (Symposium D)

Lila J. Chamberlain, Massachusetts Institute of Technology, "Cellular Reaction to Synthetic and Natural Polymeric Tube Implants Used for Peripheral Nerve Regeneration" (Symposium O)

Danielle R. Chamberlin, University of California—Berkeley, "Multivalent Acceptor Doped Germanium Lasers: A Solid-State Tunable Source From 75 to 300 μm " (Symposium F)

Jinghong Chen, University of Southern California, "High E-O Coefficient Polymers Based on a Chromophore Containing Isophorone Moiety for Second-Order Nonlinear Optics" (Symposium J)

Anthony D. Dinsmore, University of Pennsylvania, "Hard Spheres Inside Vesicles: Depletion Forces and Membrane Curvature" (Symposium L)

Stephen A. Empedocles, Massachusetts Institute of Technology, "Photoluminescence Spectroscopy of Single CdSe Nanocrystallite Quantum Dots"

(Symposium C)

Michael Fasolka, Massachusetts Institute of Technology, "Observed Substrate Topography-Mediated Lateral Patterning of Diblock Copolymer Films" (Symposium N)

Jennifer A. Hollingsworth, Washington University, "Spray Chemical Vapor Deposition of CuInS₂ Thin Films: The Influence of Deposition Conditions on Film Quality" and "Low-Temperature, Solution-Based Route to Nano-Indium Sulfide Phases and a New Chemical-Bath Process for Deposition of Orthorhombic InS Thin Films" (Symposium W)

C. Esther Jesurum, Massachusetts Institute of Technology, "Modeling Collision Cascade Structure of SiO₂, Si₃N₄, and SiC Using Local Topological Approaches" (Symposium KK)

Bijaya B. Karki, University of Edinburgh, "High Pressure Elasticity of the Major Silicate and Oxide Minerals of the Earth's Lower Mantle" (Symposium DD)

Ilya Koltover, University of California—Santa Barbara, "Structure and Interactions in Self-Assembled DNA-Cationic Lipid Complexes in the Presence of Single and Multivalent Counterions" and "Melting and Interactions in Multilayers of Two-Dimensional Crystals of Membrane-Protein Bacteriorhodopsin" (Symposia K and L)

Francois Leonard, University of Toronto, "Alloy Decomposition and Surface Instabilities in Thin Films" and "Phase Separation in Heteroepitaxial Thin Film Growth" (Symposium A)

Alexander V. Mamishev, Massachusetts Institute of Technology, "Measurement of Stratified Distributions of Dielectric Properties and Dependent Physical Variables" (Symposium EE)

Jeffery B. Maxson, University of Wisconsin—Madison, "Comparative Studies of the Surface of GaN (0001) Thin Films with LEEM" (Symposium D)

Robert C. Mucic, Northwestern University, "Functional DNA/Nanoparticle-Based Materials" (Symposium FF)

Michael Natusch, University of Cambridge, "Local Electronic Structure of Defects in GaN from Spatially Resolved Electron Energy-Loss Spectroscopy (EELS)" (Symposium D)

Ainissa G. Ramirez, Stanford University, "Influence of Annealing on the Microstructure of Amorphous Carbon Thin Films for Magnetic Hard Disks" (Symposium AA)

Rajesh A. Rao, Duke University, "Effect of Substrate Miscut and Lattice Mismatch on Grown Mechanisms of Epitaxial Metallic Oxide SrRuO₃ Thin Films" and "Effect of Domain Structure on the Magnetoresistance of Epitaxial Thin Films of Ferromagnetic Metallic Oxide SrRuO₃" (Symposia A and V)

Lars Rebohle, Forschungszentrum Rossendorf, "Strong Blue and Violet Light Emission from Silicon and Germanium Implanted Silicon Dioxide" (Symposium H)

Serge Santos, Swiss Federal Institute of Technology, "A Novel Parallel-Rotation Algorithm for Atomistic Monte Carlo Simulation of Polymer Melts and Glasses" (Symposium P)

Michael C. Wanke, University of California—Santa Barbara, "Laser CVD Rapid Processing of Ceramic Photonic Band-Gap Microstructures" (Symposium W)

Andre Wong, University of British Columbia, "Stability of Magnesium Implanted YBa₂Cu₃O₇ Thin Films" (Symposium T)

Ke Yang, University of Massachusetts, "Three Dimensional Quantum Confinement in Gallium Nitride Nanoparticles" and "Characterizing the NLO Chromophore Orientation of Polymeric Film by Electroabsorption Spectroscopy" (Symposia C and J)

Stefano Zapperi, Boston University, "Driven Dynamics of a Ferromagnetic Domain Wall: A Theory for the Barkhausen Effect" (Symposium B)

MRS

The MRS Exhibit, held in conjunction with the 1997 MRS Fall Meeting, will encompass the full spectrum of equipment, instrumentation, products, software, publications and services for materials research. As always, the exhibit will closely parallel the nature of the symposia, and the technical program has been arranged to allow meeting participants ample opportunity to attend the exhibit. MRS encourages attendees to visit the exhibit by scheduling coffee breaks, deli-style lunches, and a meeting-wide reception in University Hall.

EXHIBIT HOURS

	Marriott Hotel University Hall & Atrium Lounge	Westin Hotel 3rd & 4th Floors
Tuesday, December 2	11:30 a.m. - 6:30 p.m.	9:30 a.m. - 5:00 p.m.
Wednesday, December 3	9:30 a.m. - 5:00 p.m.	9:30 a.m. - 5:00 p.m. 7:30 p.m. - 10:00 p.m.
Thursday, December 4	9:30 a.m. - 2:30 p.m.	9:30 a.m. - 1:30 p.m.

Complimentary Reception will be held in University Hall on Tuesday evening from 5:00 p.m. to 6:30 p.m.

PARTIAL LIST OF 1997 FALL EXHIBITORS

Products & Services

A & N Corporation
Advanced Research Systems
AlXTRON, Inc.
AJA International, Inc.
Alcatel Vacuum Products, Inc.
Aldrich Chemical Company, Inc.
Alfa Aesar, a Johnson Matthey Company
Amptek, Inc.
Andeen-Hagerling, Inc.
Angstrom Sciences
APD Cryogenics, Inc.
ASTeX/Applied Science and Technology, Inc.
Australian Scientific Instruments
Barnstead/ThermoLyne Corporation
Barr Associates, Inc.
Bede Scientific Incorporated
BetaBeam
Bio-Logic Co.
Blake Industries, Inc.
Bruker Analytical X-Ray Systems, Inc.
Buehler Ltd.
Burleigh Instruments, Inc.
Cameca Instruments, Inc.
CAPE Simulations, Inc.
CERAC, Inc.
Ceramaseal
CHA Industries
Chemglass, Inc.
Commonwealth Scientific Corporation
Cree Research, Inc.
CRI, Inc.
Cryomech, Inc.
CrysTec
DCA Instruments, Inc.
Denton Vacuum, Inc.
Digital Instruments, Inc.
Diversified Technologies, Inc.
Duniway Stockroom Corp.
Dynamic Systems Inc.
EDAX International
Edwards High Vacuum International
EMCORE Corporation
EMISPEC Systems, Inc.
Epichem Inc.
EPI MBE Products Group
Epion/PVD Products
Epitaxial Technologies, LLC
Epitronics Corp./ATMI
ESCETE B.V.
ESM Software
Evans East

E.A. Fischione Instruments, Inc.
Gatan, Inc.
General Vacuum, Inc.
Glassman High Voltage, Inc.
Goodfellow Corporation
High Voltage Engineering Europa B.V.
Hinds Instruments, Inc.
Hitachi Scientific Instruments
Huntington Mechanical Laboratories, Inc.
Hysitron Incorporated
IBM Analytical and Test Services
Implant Sciences Corporation
Industrial Science & Technology Network
Inel, Inc.
Innotec Group, Inc.
InnoVac Corporation
Innovative Technology, Inc.
Inorgtech
Instruments SA, Inc.
Insulator Seal Incorporated
Ion Tech, Inc.
Janis Research Company, Inc.
JCPDS-ICDD
JEOL USA, Inc.
Johnson Matthey Electronics
k-Space Associates, Inc.
Kaiser Optical Systems, Inc.
Keithley Instruments, Inc.
Kevex Instruments, Inc.
Kimbal Physics Inc.
KLA-Tencor
Kratos Analytical Inc.
Ladd Research Industries, Inc.
Lake Shore Cryotronics, Inc.
Lambda Physik, Inc.
Lambda Technologies
Leighton Electronics, Inc.
Kurt J. Lesker Company
Leybold Inficon Inc.
LUXTRON Corporation
Magnet Sales & Manufacturing
MARCH Instruments, Inc.
M. Braun, Inc.
MCNC
MDC Vacuum Products Corporation
Micrion Corporation
Micro Photonics, Inc.
Microcal Software, Inc.
Micropyretics Heaters International Inc. (MHI Inc.)
MKS Instruments, Inc.
MMR Technologies, Inc.
Modasco, Inc.

Molecular Metrology, Inc.
Molecular Simulations, Inc.
Morton International, Inc.
MTI Corporation
Nano Instruments, Inc.
National Electrostatics Corporation
Naval Research Laboratory (NRL)
Neocera, Inc.
NFT-Nanofilm Technologie GmbH
Nicolet Instrument Corporation
NORAN Instruments, Inc.
Noranda Advanced Materials
NOVOCONTROL
NYS Center for Advanced Thin Film Technology
Olympus America Inc.
Omicron Associates
On-Line Technologies, Inc.
Osaka Vacuum, Ltd.
Osmic, Inc.
Oxford Applied Research
Oxford Instruments America, Inc.
Park Scientific Instruments
Pfeiffer Vacuum Technology
Philips Analytical X-Ray
Philips Electron Optics Inc.
Physical Electronics, Inc.
Praxair Specialty Ceramics
Princeton Gamma-Tech, Inc.
Princeton Instruments, Inc.
Princeton Scientific Corp.
Pure Tech, Inc.
Quad Group, Inc.
Quantum Design, Inc.
Quesant Instrument Corporation
Radiant Technologies, Inc.
Renishaw Inc.
Research and PVD Materials Corporation
Riber Division/ISA Inc.
Rigaku/USA, Inc.
RJ Lee Instruments, Ltd.
RMC
SC Technology/Telemark
Scintag Inc.
SiCrystal AG
SKION Corporation
Solartron Inc.
Solas Ltd.
SOPRA, Inc.
South Bay Technology, Inc.
SPECS USA, Inc.
SPI Supplies/Structure Probe, Inc.
Staub Instruments
Strem Chemicals, Inc.

Structured Materials/
Nanopowder Enterprises
Struers/Logitech Product Group
Superconductive Components, Inc.
SURFACE
Surface/Interface, Inc.
SurForce Corporation
SVT Associates, Inc.
Sycon Instruments, Inc.
TECHNOTRADE International, Inc.
TexSEM Laboratories, Inc. (TSL)
Thermionics Vacuum Products
Thomas Swan & Co., Ltd.
TopoMetrix Corp.
ULTRA TEC Mfg., Inc.
Union Carbide Crystal Products
Vacuum Atmospheres Company
Vacuum Research Corporation
Varian Vacuum Products
VAT, Inc.
Virginia Semiconductor, Inc.
Voltaix, Inc.
VSI Vacuum Science Instruments, Inc.
R.D. Webb Company
Well Diamond Wire Saws, Inc.
J.A. Woollam Co., Inc.
X-ray Instrumentation Associates
X-Ray Optical Systems, Inc.
Zygo Corporation

Books & Software

Academic Press, Inc.
American Ceramic Society (ACerS)
American Chemical Society
American Institute of Physics, Inc.
American Physical Society
ASM International
Cambridge University Press
Chapman & Hall
Compound Semiconductor Magazine
Elsevier Science
Gordon and Breach/Harwood Academic
IOP Publishing Inc.
Kluwer Academic Publishers
Oxford University Press
Plenum Publishing Corporation
Springer-Verlag New York, Inc.
Taylor & Francis
WCB/McGraw-Hill
John Wiley & Sons, Inc.

(as of September 1997)

- ABB Extrel
- Advanced Control Systems Corporation
- Advanced Energy Industries, Inc.
- Advanced Micro Devices, Inc.
- AEA Technology
- Aerospace Corporation
- Aetrium, Inc.
- AG Associates
- Air Products and Chemicals, Inc.
- AIXTRON, Inc.
- AKZO Nobel Chemicals, Inc.
- Aldrich Chemical Company, Inc.
- AlliedSignal, Inc.
- Aluminum Company of America
- Ames Laboratory
- Amptek, Inc.
- AMRAY, Inc.
- APD Cryogenics, Inc.
- Applied Materials-Applied Komatsu Technology
- Applied Materials-Implant Division
- Applied Materials-RTP Product Division
- ARCO Chemical Company
- Argonne National Laboratory
- Asahi Glass Co., Ltd.
- Ashland Chemical Co.
- ASM
- AST elektronik GmbH
- ASTeX/Applied Science and Technology, Inc.
- Baikowski International Corporation
- Battelle Pacific Northwest Labs
- Bede Scientific Incorporated
- Bell Laboratories, Lucent Technologies
- BIOMET Incorporated
- Blake Industries, Inc.
- BP International Limited
- Brookhaven Instruments Incorporated
- Brookhaven National Laboratory
- Bruker Analytical X-Ray Systems, Inc.
- Bruker Instruments, Inc.
- Bunkoh-Keiki Co., Ltd.
- Burleigh Instruments, Inc.
- Cameca Instruments, Inc.
- Canon, Inc.
- CEA-LETI
- Chemat Technology, Inc.
- Chemipro Kasei Kaisha, Ltd.
- Chichibu Onoda Cement Co.
- City Technology Limited
- CNR-IMETEM
- Coherent, Inc./Laser Group
- Commonwealth Scientific Corporation
- Conductus, Inc.
- Consortium für Elektrochemische Industrie GmbH
- Continental Electronics Corporation
- Co.Ri.M.Me
- Corning Incorporated
- Cree Research, Inc.
- Criterion Catalyst Company L.P.
- CVC
- Cymer, Inc.
- Dainippon Screen Manufacturing Co., Ltd.
- Danfysik A/S
- DCA Instruments, Inc.
- Denton Vacuum, Inc.
- Diamond Semiconductor Group
- Diatome U.S.
- Digital Instruments, Inc.
- Digital Semiconductor (A Digital Equipment Corporation)
- Dow Chemical Company
- Dow Corning Corporation
- dpIX, a Xerox Company
- DSM Research
- Dupont Company, Central Research and Development
- Dytech Corporation, Ltd.
- Eastman Kodak Company
- Eaton Corporation
- Eaton Thermal Processing Systems
- EDAX International
- EG&G Instruments, Inc.
- EG&G Ortec
- Electric Power Research Institute
- Elsevier Science B.V.
- Elsevier Science Ltd.
- EMCORE Corporation
- Energy Conversion Devices, Inc.
- E.O. Lawrence Berkeley National Laboratory
- EPI MBE Products Group
- ESM Software
- Charles Evans & Associates
- Evans East
- Exxon Production Research Company
- Exxon Research and Engineering Company
- FEI Company
- FHR Anlagenbau GmbH
- E.A. Fischione Instruments, Inc.
- Ford Motor Company
- Forschungszentrum Rossendorf e.V.
- Freund Publishing House, Ltd.
- FSI International
- Fuji Electric Co., Ltd.
- Fujikin of America, Inc.
- Fujikin Incorporated
- Fujitsu, Ltd.
- Furukawa Electric Co., Ltd.
- Futaba Corp.
- Gatan, Inc.
- Gelest, Inc.
- Genentech, Inc.
- General Electric Company
- General Motors Research & Development
- GMW Associates
- Goodfellow Corporation
- Gordon and Breach
- Gould Electronics Inc.
- POWERDEX Division
- Granville-Phillips Company
- Harris Diamond Corporation
- Hewlett Packard Company
- Optoelectronics Division
- Hewlett Packard Laboratories Japan, Inc.
- Hewlett Packard, NMD
- High Voltage Engineering Europa B.V.
- Hitachi Europe Ltd.
- Hitachi, Ltd.
- Hitachi Scientific Instruments
- Hoechst Celanese Corporation
- Advanced Technology Group
- Hoechst Celanese Corporation Separations Products Division
- Hughes Research Laboratories
- Huntington Mechanical Laboratories, Inc.
- Hysitron, Inc.
- IBM Analytical and Test Services
- IBM Corporation-Thomas J. Watson Research Center
- ICI Acrylics
- IMES Co., Ltd.
- Initiative Scientific Products
- Inorgtech, Ltd.
- Institut für Schicht und Ionentechnik (ISI)
- Institute for Scientific Information
- Instron Corporation
- Insulator Seal, Inc.
- Intel Corporation
- Ion Tech, Inc.
- ITAC, Ltd.
- JCPDS-International Centre for Diffraction Data
- JEOL USA, Inc.
- Johnsen Ultravac
- Johnson Controls, Inc.
- Johnson & Johnson Professional
- Johnson Matthey Electronics
- k-Space Associates, Inc.
- Kaneka Corporation
- Keithley Instruments, Inc.
- Kimball Physics, Inc.
- KLA-Tencor
- Kobe Steel USA, Inc.
- Electronic Materials Center
- Komag, Inc.
- Komatsu Electronic Metals Co., Ltd.
- Kratos Analytical, Inc.
- Lake Shore Cryotronics, Inc.
- Lambda Physik, Inc.
- Lambda Technologies, Inc.
- Lawrence Livermore National Laboratory
- Leica Inc.
- LEO Electron Microscopy Inc.
- Kurt J. Lesker Company
- Leibold Systems GmbH
- Leibold Vacuum Products, Inc.
- Los Alamos National Laboratory
- Materials Analysis Group
- Philips Semiconductors
- Materials Research Corporation
- Materials Research Group, Inc.
- Matsushita Electric Industrial Co.
- Matsushita Electronics Corp.
- Mattson Technology, Inc.
- MDC Vacuum Products Corporation
- MEL Chemicals
- MEMC Electronic Materials, Inc.
- Micrion Corporation
- Micro Photonics, Inc.
- Microwave Research Center
- Millipore Corporation
- Mitsubishi Electric
- Semiconductor Laboratories
- Mitsubishi Materials Corporation
- Mitsubishi Silicon America
- Mitsui-Toatsu Chemicals, Inc.
- MKS Instruments, Inc.
- MMR Technologies, Inc.
- Mobil Technology Company
- Molecular Imaging Corporation
- Molecular Simulations, Inc.
- Morita Chemical Industries
- Morton International, Inc.
- Motorola
- MR Semicon, Inc.
- MVSystems, Inc.
- n&k Technology, Inc.
- Nanophase Technologies Corporation
- NAPS France
- National Electrostatics Corp.
- National Semiconductor Corporation
- National Technology Transfer Center
- NEC Corporation
- NEC Research Institute, Inc.
- Neocera, Inc.
- New Focus, Inc.
- Nichia Chemical Industries, Ltd.
- Niki Glass Co., Ltd.
- Nikko Hitech International, Inc.
- Nippon Steel Corporation
- Noranda Advanced Materials
- Nor-Cal Products, Inc.
- Northrop Grumman
- Science & Technology Center
- NSA Nissei Sangyoi America
- Oak Ridge National Laboratory
- Oldham S.A. France
- Omicron Associates
- OnTrak Systems, Inc.
- Osmic, Inc.
- Oxford Cryosystems
- Oxford Instruments America, Inc.
- Park Scientific Instruments
- Parke Mathematical Laboratories
- Pfeiffer Vacuum Technology, Inc.
- Philips Electron Optics
- Philips Electronic Instruments Company
- Philips Research
- Physical Electronics, Inc. (PHI)
- PIOLAX Incorporated
- Plasma-Therm, Inc.
- Plenum Publishing Corporation
- Portland Cement Association
- Power Reactor & Nuclear Fuel Development Corporation
- President Enterprises Co.
- Princeton Gamma-Tech, Inc.
- Princeton Measurements Corporation
- Pure Tech, Inc.
- Quantum Design, Inc.
- Renishaw PLC
- Research and PVD Materials Corporation
- RHK Technology, Inc.
- Riber Division/ISA Inc.
- Rigaku/USA, Inc.
- RIMCOF (R&D Institute of Metals & Composites for Future Industries)
- RJ Lee Instruments, Ltd.
- R.M.D. Inc.
- Rockwell International Science Center
- Rohm and Haas Company
- Samsung Advanced Institute of Technology
- Sandia National Laboratories
- Sanyo Electric Co., Ltd.
- Sanyo Vacuum Industries Co.
- Schering Plough Research Institute
- Schlumberger Cambridge Research
- Schlumberger Industries
- Schumacher, Unit of Air Products & Chemicals
- SCP Global Technologies
- Screen DNS Electronics
- Seagate Technology, Inc.
- SEH America, Inc.
- Sematech, Inc.
- Semiconductor Processing Company
- Semitool, Inc.
- SensArray Corporation
- SENTECH Instruments
- SGS-Thomson Microelectronics
- Sharp Corporation
- Sharp Microelectronics Technology, Inc.
- Shell Chemical Company
- Shin-Etsu Handotai Co., Ltd.
- Shining Surface Systems
- SIGe Microsystems Technology, Inc.
- SKC America, Inc.
- Smith & Nephew Research, Ltd.
- SOITEC/USA, Inc.
- Solarex
- Solartron
- SONY Corporation
- South Bay Technology, Inc.
- Southwire Company
- Spire Corporation
- Springer-Verlag New York, Inc.
- STAIR Instruments, Inc.
- Stream Chemicals, Inc.
- SubMicron Systems Corporation
- SULA Technologies
- Sumitomo Electric Industries, Ltd.
- Information & Electronics Laboratory
- Sumitomo Electric Industries
- Itami Research Laboratories
- Sumitomo Electric USA, Inc.
- Sumitomo Sitix Corporation
- Supelec (a.k.a. Electricite de France)
- SURFACE
- Surface/Interface, Inc.
- SVT Associates
- Taisil Electronic Materials Corp.
- Technology Modeling Associates
- Telefunken Microelectronic
- Telemark
- Texas Instruments, Inc.
- Thermionics Laboratory, Inc.
- 3M Industrial and Consumer Sector Research Laboratory
- Thomas Swan & Co., Ltd.
- TLI Enterprises
- Tokeyon Electron Limited
- Topcon Technologies Inc.
- TopoMetrix Corporation
- Toshiba Corporation
- Tosoh SMD, Inc.
- Toyota Gosei Co., Ltd.
- Toyota Central R&D Laboratories
- TRW Space & Defense
- Union Carbide Corporation
- United Microelectronics Corporation
- United Solar Systems Corp.
- Universal Display Corporation
- UOP Research Center
- US, Inc.
- Vanguard International Semiconductor Corp.
- Varian Associates, Inc.
- Virginia Semiconductor, Inc.
- Virtual Laboratories
- Voltaix, Inc.
- VSI Vacuum Science Instruments
- VSP—International Science Publishers
- Wacker Siltronic AG
- John Wiley & Sons, Ltd./VCH
- W.R. Grace & Company
- Xerox Corporation
- Zentrum Mikroelektronik Dresden GmbH

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